



CSP-48 Lead Free RoHS Profile

Total Mass of the Unit specified (g):	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.034	48 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	24.18960	713,096	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.01445	426	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.00898	265	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.00449	132	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.00449	132	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.03576	1,054	
		Metalization	BCB			0.05432	1,601	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	9.17753	270,548	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.38435	11,330	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.048	1,415	

Total mass (mg)	33.922
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